



SOLDER PASTE SC TH4NN

Water washable

The solder paste SOLDER CHEMISTRY SC TH4NN is a high tech product whose flux can be easily removed with water, before and after soldering. The development is based on the high demands of clients in the field of the **SMT devices (SMD) production**.

SC TH4NN is a homogeneous mixture of solder powder, in all required alloys and grain sizes, and an organic flux based on water washable rosin, halogen- and halide-free. The flux corresponds to F-SW 33 according to DIN 8511 and thus SC TH4NN is one of the very best water washable solder pastes.

Besides excellent slump resistance, no solder balling, a long stencil and tack life and high temperature stability, this paste has following advantages:

- *SC TH4NN* soft, only with water washable residue
- *SC TH4NN* totally resistant to humidity – for days!
- *SC TH4NN* high tack even after hours
- *SC TH4NN* superior soldering results with bright joints even after washing
- *SC TH4NN* excellent for fine and ultra fine pitch applications

PHYSICAL PROPERTIES:

<u>Preferred alloys</u>	Melting point	According to international standards we deliver these alloys in the classes of:
Sn10/Pb88/Ag2	258-290°C	class 3 25 - 45 µm class 4 20 - 36 µm class 5 10 - 25 µm
Sn5Pb95	308-312°C	
Sn2/Pb95,5/Ag2,5	305°C	
Sn5/Pb92,5/Ag2,5	280-284°C	
Sn1/Pb97,5/Ag1,5	309°C	

VISCOSITY (Pa.s) in range measured with Brookfield RVT-DV-II viscometer at 75% metal content

Grain size	Viscosity
Fine (T3)	115 - 140

S.I.R. AND ELECTROMIGRATION comparable to DIN 32513

The figures of SIR correspond to those of the circuit boards, because the residues **have to be(!)** completely washed away with only hot water, it means without any additives like cleaner!

QUALIFICATION

SC TH4NN is a water soluble paste, which fulfils the demands of the leading companies in the SMD field. The corrosion and wetting tests have been passed. Laboratory tests certify non-corrosive residues, according to F-SW 33, which should be completely washed away from the circuit board, because of their water solubility.

STORAGE

Unopened at room temperature (20°C/68°F): 6 months

Open or on the printer squeegee the processing time of course depends on the environmental influences, but in normal praxis 16h of processing time have been reached.

APPLICATION INFORMATION

After using the paste close the container tightly.

Do not mix used and fresh paste, only to freshen up paste and only at work in progress.

Do not mix pastes of different kind.

Recommended squeegee speed: 15-100 mm/s.

Note: the printer is always faster than the fastest assembler in the production line.

The printer squeegee must be set to ensure that the paste performs a rolling action in front of the squeegee and does not slide!

The stencil can be washed with an alcohol mixture or water. The alcohol must not contaminate fresh paste.

The paste is suitable for all common reflow systems.

Note:

The residue of our paste is before and after soldering 100% biodegradable! The sewage pollution after the use of 2kg of SC TH4NN is less than a washing (5 kg of laundry) in an average household.

Solder Chemistry order example

Paste	Grain size	Alloy	Flux content	Jar capacity
SC TH4NN	T3	10/88/2Ag	25%	500 g

Order example after DIN:

Solder Paste SC TH4NN L-Sn10Pb88Ag2 / F-SW33 / 75-3 500 g (packing)

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